

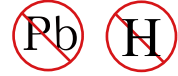


DATA SHEET

SEMICONDUCTOR

YSCKSD130DT4

HIGH CURRENT SURGE PROTECTION DIODE ARRAY



APPLICATIONS

- ◆ ADSL Lines
- ◆ I²C Bus Protection
- ◆ Video Line Protection
- ◆ T1/E1 secondary IC Side Protection
- ◆ Portable Electronics
- ◆ Microcontroller Input Protection
- ◆ WAN/LAN Equipment
- ◆ ISDN S/T Interface

IEC COMPATIBILITY

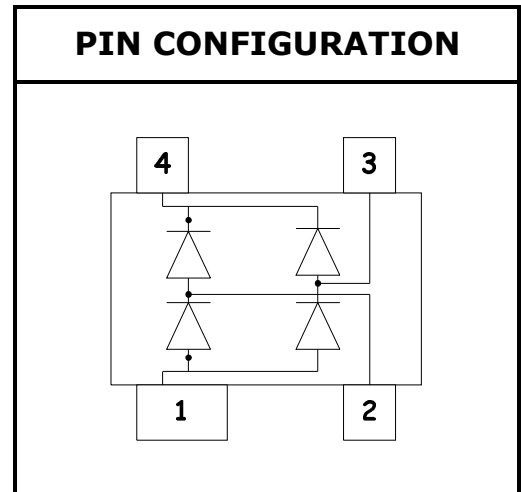
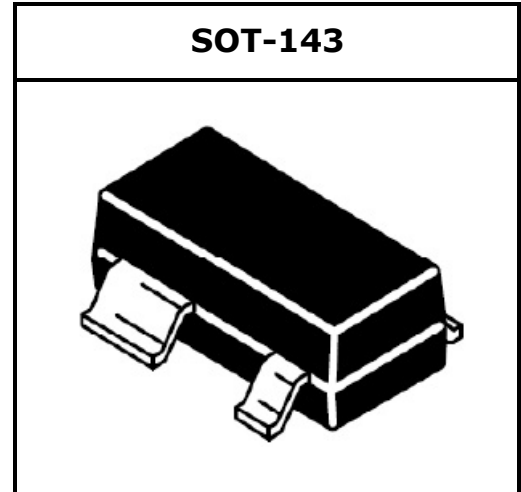
- ◆ IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- ◆ IEC61000-4-4 (EFT) 40A (5/50 η s)
- ◆ IEC61000-4-5 (Lightning) 24A (8/20 μ s)

FEATURES

- ◆ Array of surge rated, low capacitance diodes
- ◆ Protects two I/O lines
- ◆ Low capacitance (5pF typical) for high-speed interfaces
- ◆ Low clamping voltage
- ◆ RoHS Compliant

MECHANICAL CHARACTERISTICS

- ◆ SOT-143 package
- ◆ Molding Compound Flammability Rating : UL 94V-0
- ◆ Weight 10 Milligrams (Approximate)
- ◆ Quantity Per Reel : 3,000pcs
- ◆ Reel Size : 7 inch
- ◆ Lead Finish : Lead Free



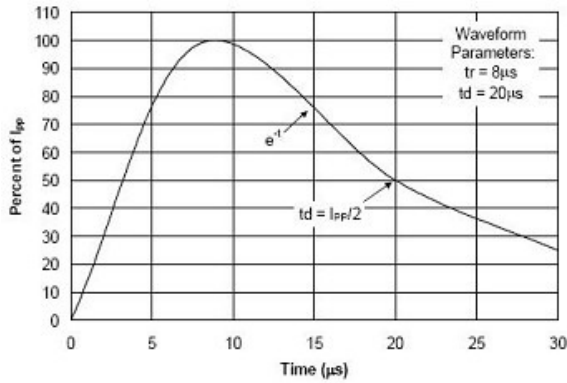
DEVICE CHARACTERISTICS

YSCKSD130DT4

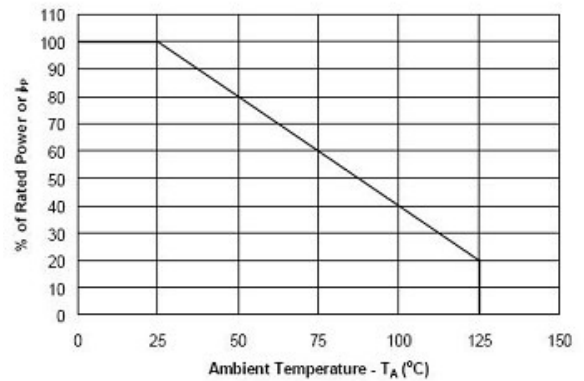
MAXIMUM RATINGS (@ 25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Surge Current (tp = 8/20μs)	I _{PP}	24	A
Rectifier Repetitive Peak Reverse Voltage	V _{RRM}	70	V
Lead Soldering Temperature	T _L	260 (10 sec.)	°C
Operating Temperature Range	T _J	-55 ~ 150	°C
Storage Temperature Range	T _{STG}	-55 ~ 150	°C

ELECTRICAL CHARACTERISTICS PER LINE (@ 25°C Unless Otherwise Specified)									
PART NUMBER	DEVICE MARKING	V _{RRM}	V _B	I _T	V _{FC}	V _{FC}		I _R	C _T
		(V) (max.)	(V) (min.)	(μA)	@1A (max.)	(max.)	(@A)	(μA) (max.)	(pF) (typ.)
YSCKSD130DT4	CKA	70	100	50	1.5	8	24	1	5

Pulse Waveform

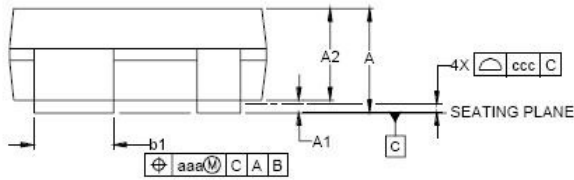
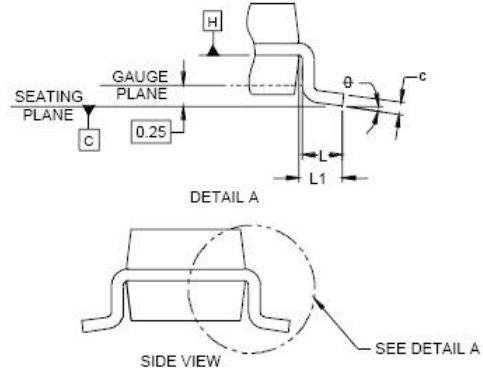
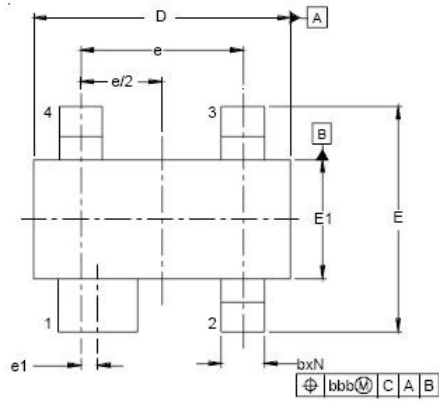


Power Derating Curve



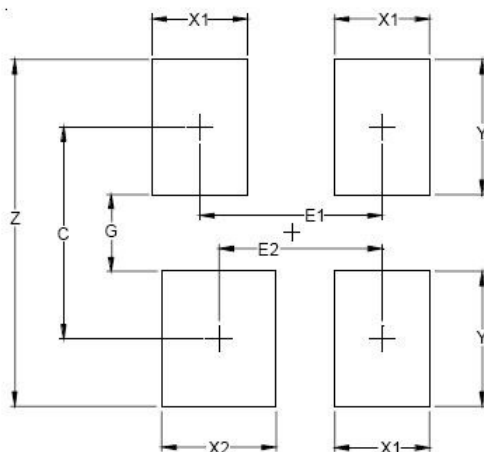
PACKAGE OUTLINE & DIMENSIONS

YSCKSD130DT4



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.031	-	.048	0.80	-	1.22
A1	.000	-	.006	0.013	-	0.15
A2	.029	.035	.042	0.75	0.90	1.07
b	.011	-	.020	0.30	-	0.51
b1	.029	-	.037	0.76	-	0.94
c	.003	-	.008	0.08	-	0.20
D	.110	.114	.120	2.80	2.90	3.04
E	.082	.093	.104	2.10	2.37	2.64
E1	.047	.051	.055	1.20	1.30	1.40
e	.075			1.92 BSC		
e1	.008			0.20 BSC		
L	.015	.020	.024	0.40	0.50	0.60
L1	(.021)			(0.54)		
N	4			4		
θ	0°	-	8°	0°	-	8°
aaa	.006			0.15		
bbb	.008			0.20		
ccc	.004			0.10		

* SOLDERING FOOTPRINT



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.087)	(2.20)
E1	.076	1.92
E2	.068	1.72
G	.031	0.80
X1	.039	1.00
X2	.047	1.20
Y	.055	1.40
Z	.141	3.60